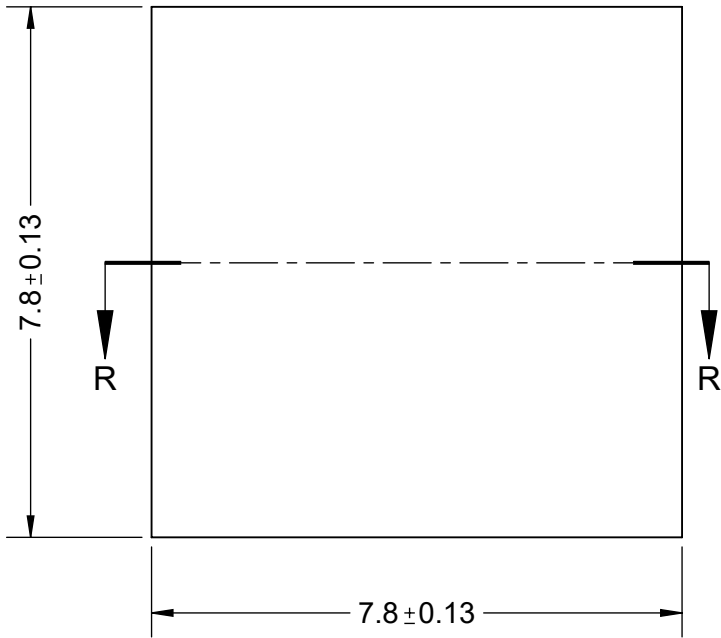
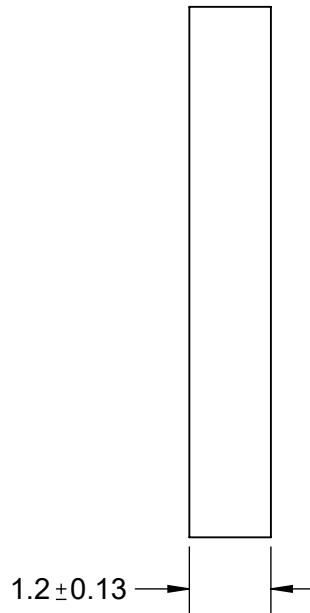


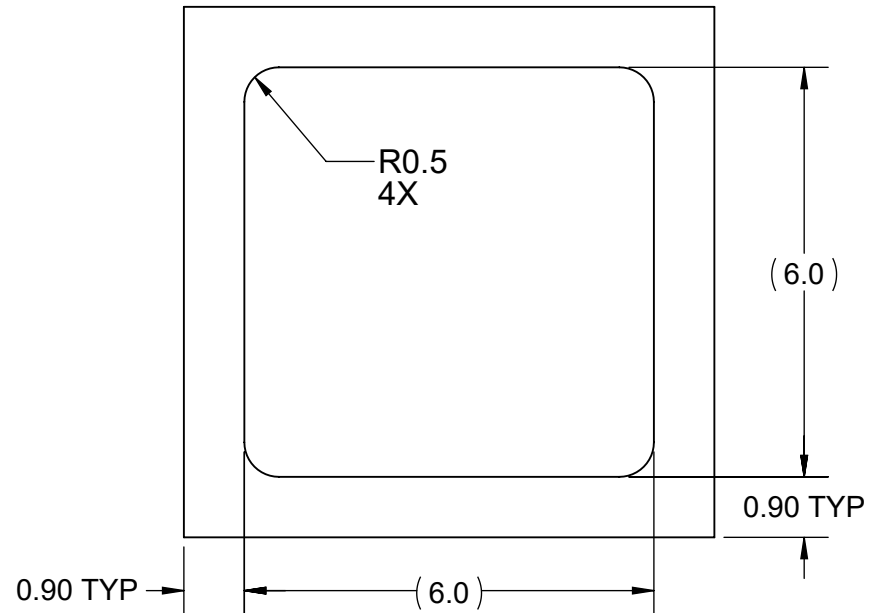
**TOP VIEW**



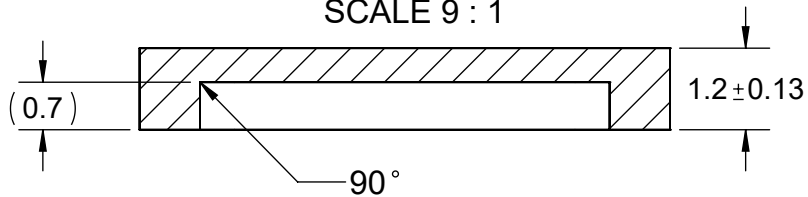
**SIDE VIEW**



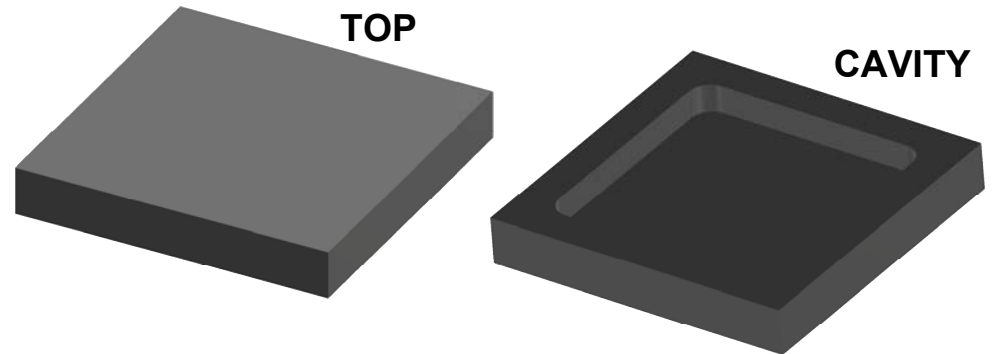
**BOTTOM VIEW**



**SECTION R-R  
SCALE 9 : 1**



**MODELS**



Notes: (Unless Otherwise Specified)

- 1) MATERIAL:  
A. SEMICONDUCTOR GRADE MOLD COMPOUND  
B. PREFORM: NONE
- 2) LID ATTACH:  
USE EPOXY PER CUSTOMER CHOICE
- 3) STORAGE: NO LIMIT @ 25°C
- 4) COLOR: BLACK
- 5) DIMENSIONS mm

APPROVALS	DATE	<b>Mirror</b> Semiconductor™			
DRAWN T. Au	5/3/2024				
ENG M. Hart	5/3/2024	TITLE M-CAP7.8T1.2-BLACK 7.8 x 7.8mm DOME LID			
MFG		SCALE 15:1	SIZE A	DRAWING NO. 278450	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

# PART NUMBERING SYSTEM

**M**

-

**CAP**

**7.8**

**T**

**1.2**

-

**BLACK**

**SERIES**

MOLD COMPOUND  
G770H Semiconductor Grade  
Without Adhesive Preform

**SHAPE**

CAP = DOME  
CAVITY LID

**SIZE OUTLINE**

CODE	MM	INCH
7.8	7.80	0.307

**HEIGHT OD**

CODE	MM	INCH
1.2	1.20	0.0472

**COLOR**

BLACK

**PACKAGING**

CODE	PACKAGING
T	TRAY
B	BULK

**Mirror**  
Semiconductor™

TITLE M-CAP7.8T1.2-BLACK  
7.8 x 7.8mm DOME LID

SCALE	SIZE	DRAWING NO.	REV
NONE	A	278450	A

DO NOT SCALE DRAWING

SHEET 2 OF 2